



FABRICATION NOTE:

- 1:FABRICATE USING LATEST REVISION OF IPC-6012A CLASS 2 OR ABOVE
- 2:FABRICATE USING MASTER ARTWORK EVLSRK1000 SOT23 PFLAT R1 FOR CIRCUIT PATTERN
NO DEVIATION FROM MASTER ARTWORK ARE PERMITTED WITHOUT WRITTEN APPROVAL FROM AN AUTHORIZED STMicroelectronics REPRESENTATIVE
- 3:VENDOR MUST BE UL QUALIFIED AND BOARDS MUST BE IDENTIFIED WITH APPROPRIATE VENDOR UL IDENTIFICATION MARK, LOT OR JOB NUMBER AND PCB MATERIAL FLAMMABILITY RATING (94V-0) MINIMUM
- 4:MATERIAL: FR4 RoHS COMPLIANT MINIMUM 125 C
SEE "DETAIL 'A'" FOR BOARD THICKNESS, COPPER WEIGHT AND LAYER CONSTRUCTION
- 5:GREEN SOLDER MASK BOTH SIDE OF BOARD WITH LIQUID PHOTO IMAGEABLE SOLDERMASK
- 6:FINISH: HAL Lead Free
- 7:FOR SMT COMPONENTS WITH PIN PITCH OF 0.019 INCH OR MORE NO GANG RELIEF OF SOLDER MASK IS ALLOWED
- 8:SILKSCREEN TO BE WHITE, NON CONDUCTIVE, EPOXY INK OR EQUIVALENT
- 9:THIS IS NOT A CONTROLLED IMPEDANCE BOARD
- 10:DESIGNATED AREA OR INSPECTION AND TEST STAMP
- 11:ON BOTTOM PCB MUST BE IDENTIFIED MANUFACTURER LOGO AND PCB TYPE (MEANS OF MATERIAL TYPE INDICATED ON THE YELLOW CARD DOCUMENT)
- 12:VENDOR TO PROVIDE BOARD STACK-UP FOR IMPEDANCE APPROVAL PRIOR TO BOARD FABBRICATION STACK UP AND IMPEDANCE TO INCLUDE COPPER PLATING ON OUTER LAYERS.FAB DRAWING STACK-UP DIMENSION ARE PROVIDED FOR REFERENCE ONLY
- 13:TEARDROPPING OF VIAS AND PADS ALLOWED AT PAD TO TRACE INTERSECTION TO INSURE A 2MIL ANULAR RING AT THE JUNCTION
- 14:REMOVE SILKSCREEN FROM SOLDERABLE SURFACE
- 15:ALL BOARD TO BE 100% ELECTRICALLY NETLIST TESTED FOR OPENS AND ON SHORTS. APPLY TEST STAMP IN REFERENCED AREA
- 16:THIS BOARD SHALL BE FULLY COMPLIANT WITH UL796

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	FINISHED SIZE	PLATED	QTY
A	12.0	PLATED	15
B	44.0	PLATED	3

TOTAL HOLES: 18

Finished Hole Tolerance - All units are in Inches -		
Finish Hole Diameter	Plated Through Finish Hole Diameter	Non Plated Through Finish Hole Diameter
0.008"-0.013"	+0.002/-FHS"	+/-0.002"
0.014"-0.063"	+/-0.003"	+/-0.002"
0.064"-0.156"	+/-0.004"	+/-0.003"
0.157"-0.250"	+/-0.007"	+/-0.004"
0.251"and up	+/-0.007"	+/-0.005"
0.125"	Non Plated Only	+0.003/-0.000"

DETAIL 'A'

LAYER BUILD UP
(reference only)

	Cu - 105u
	CORE - 1600u
	Cu - 105u

(external Cu th are after plating)
estimated total thickness 1600u

REVISION DATE							
		Description SRK1000-SOT23-PFLAT FABRICATION DRAWING				Symbol SRK1000	
						Group	
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		linear	0 <10	>10 <50	>50 <200	>200	ANG. LES.
Drawn	date 23-June-2017	midle	±0.1	±0.2	±0.3	±0.5	±1°
Approved	date	accurate	±0.05	±0.1	±0.15	±0.25	±30°
						Material	
						Treatment and surface finishing	
						REV. 1.0	